

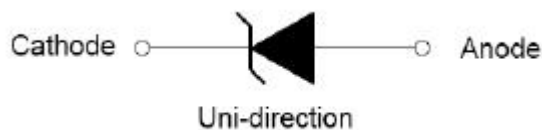
SM8S20A THRU SM8S43A TRANSIENT VOLTAGE SUPPRESSOR



Features

- Junction passivation optimized design passivated anisotropic rectifier technology
- $T_J = 175^\circ\text{C}$ capability suitable for high reliability and automotive requirement.
- Available in uni-directional polarity only
- Low leakage current
- Low forward voltage drop
- High surge capability
- AEC-Q101 qualified.

Circuit Diagram



Mechanical Data

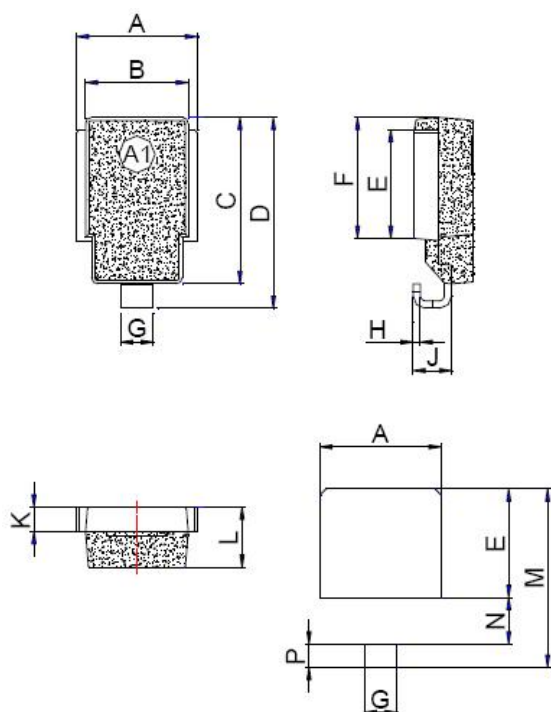
- Case: DO-218AB
- Molding compound meets UL 94V-0 flammability rating
- Base P/NHE3-RoHS-compliant, AEC-Q101 qualified
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

Maximum Ratings and Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 10/1000 μs waveform	P_{PPM}	6600	W
Peak pulse power dissipation on 10/10000 μs waveform		5200	W
Power dissipation on infinite heat sink at $T_C = 25^\circ\text{C}$	P_D	8.0	W
Peak forward surge current 8.3 ms single half sine-wave	I_{FSM}	700	A
Typical thermal resistance, junction to case	$R_{\theta JC}$	0.9	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Electrical Characteristics@T_A=25° C unless otherwise specified

DEVICE TYPE	REVERSE STAND-OFF VOLTAGE V _{RWM} (V)	BREAKDOWN VOLTAGE V _{BR} (V) @I _T		TEST CURRENT I _T	CLAMPING VOLTAGE V _C @I _{PP}	PEAK PULSE CURRENT AT 10/1000μs WAVEFORM I _{PP}	REVERSE LEAKAGE CURRENT I _R	
		MIN.	MAX.	MA	V	A	μA@25°C	μA@175°C
SM8S20A	20	22.2	24.5	5	32.4	204	5	150
SM8S22A	22	24.4	26.9	5	35.5	186	5	150
SM8S24A	24	26.7	29.5	5	38.9	170	5	150
SM8S26A	26	28.9	31.9	5	42.1	157	5	150
SM8S28A	28	31.1	34.4	5	45.4	145	5	150
SM8S30A	30	33.3	36.8	5	48.4	136	5	150
SM8S32A	32	35.5	39.4	5	51.4	128.5	5	150
SM8S33A	33	36.7	40.6	5	53.3	124	5	150
SM8S36A	36	40.0	44.2	5	58.1	114	5	150
SM8S40A	40	44.4	49.1	5	64.5	102	5	150
SM8S43A	43	47.8	52.8	5	69.4	95.1	5	150

Mechanical Dimensions DO-218AB(Inches/Millimeters)


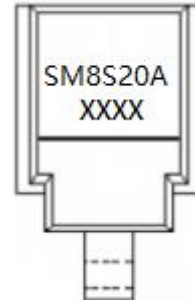
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	9.5	10.5	0.374	0.413
B	8.3	8.7	0.327	0.342
C	13.3	13.7	0.524	0.539
D	15.0	16.0	0.592	0.628
E	8.5	9.1	0.335	0.358
F	9.5	10.1	0.374	0.398
G	2.4	3.0	0.094	0.118
H	0.5	0.7	0.020	0.028
J	2.7	3.7	0.106	0.146
K	1.9	2.1	0.075	0.083
L	4.7	5.1	0.185	0.201
M	14.2	14.8	0.559	0.583
N	3.5	4.1	0.138	0.161
P	1.6	2.2	0.063	0.087

Ordering Information

Device	Package	Shipping
SM8S20A THRU SM8S43A	DO-218AB	750pcs / reel

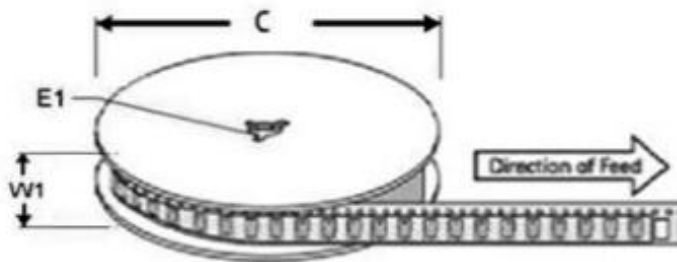
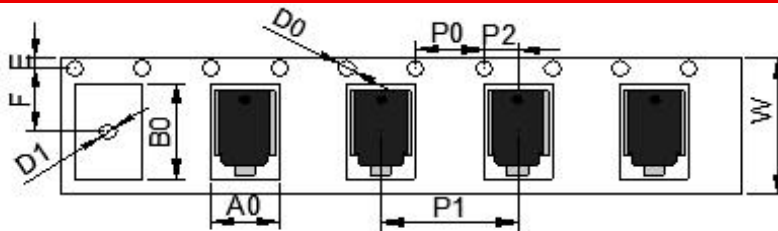
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



SM8S20A = Part Name
XXXX = Date Code

Carrier Tape Specification DO-218AB



Ref.	Dimensions	
	Millimeters	Inches
A0	10.80 ± 0.3	0.425 ± 0.012
B0	16.13 ± 0.3	0.635 ± 0.012
C	330.0 ± 0.3	13.0 ± 0.012
D0	1.55 ± 0.2	0.061 ± 0.008
D1	1.55 ± 0.2	0.061 ± 0.008
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.30 ± 0.2	0.524 ± 0.008
F	11.50 ± 0.2	0.453 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	16.00 ± 0.2	0.630 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	24.00 ± 0.2	0.945 ± 0.008
W1	25.85 ± 0.2	1.018 ± 0.008

Ratings and Characteristics Curves

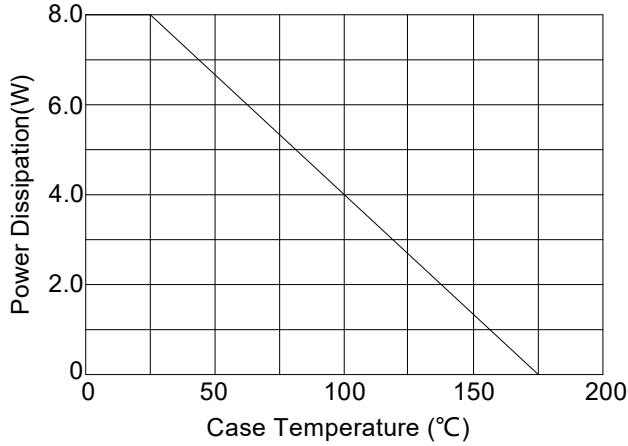


FIG.1: Power derating curve

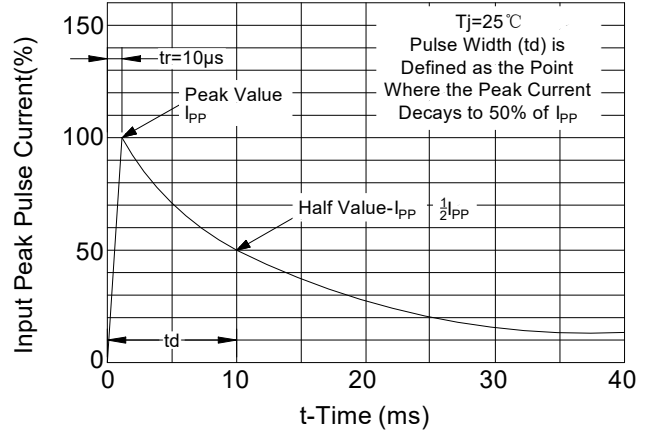


FIG.2: Pulse waveform

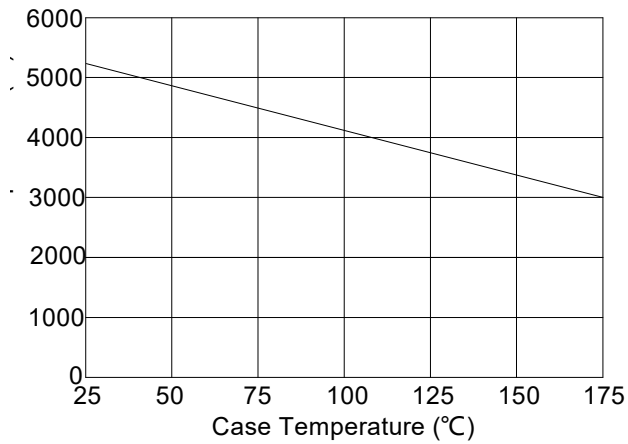


FIG.3: Load Dump Power Characteristics (10ms Exponential Waveform)

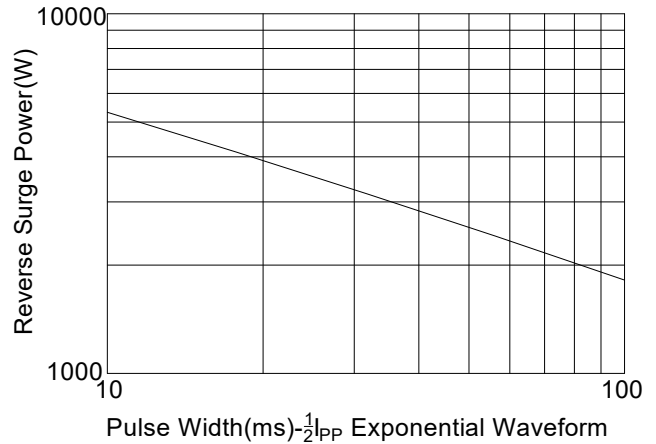


FIG.4: Reverse Power Capability

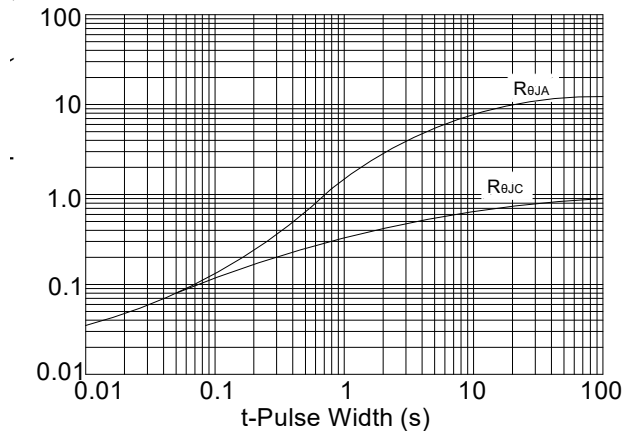


FIG.5: Typical Transient Thermal Impedance

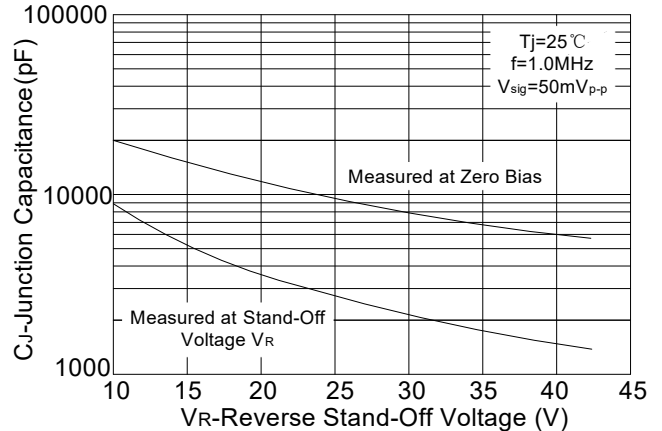


FIG.6: Typical Junction Capacitance

**Technical Data
Data Sheet N2148, Rev. -**



DISCLAIMER:

- 1- The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact the SMC - Sangdest Microelectronics (Nanjing) Co., Ltd sales department for the latest version of the datasheet(s).
- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
- 3- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any damages that may result from an accident or any other cause during operation of the user's units according to the datasheet(s). SMC - Sangdest Microelectronics (Nanjing) Co., Ltd assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in the datasheets.
- 4- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
- 5- No license is granted by the datasheet(s) under any patents or other rights of any third party or SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 6- The datasheet(s) may not be reproduced or duplicated, in any form, in whole or part, without the expressed written permission of SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 7- The products (technologies) described in the datasheet(s) are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations..